



April 2000

QFET™

FQPF12N20

200V N-Channel MOSFET

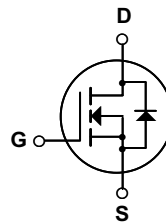
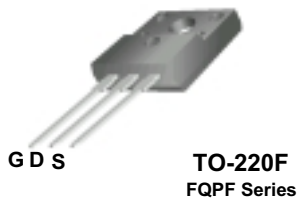
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supply, DC-AC converters for uninterrupted power supply, motor control.

Features

- 8.2A, 200V, $R_{DS(on)} = 0.28\Omega$ @ $V_{GS} = 10V$
- Low gate charge (typical 18 nC)
- Low C_{rss} (typical 18 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQPF12N20	Units
V_{DSS}	Drain-Source Voltage	200	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	8.2	A
	- Continuous ($T_C = 100^\circ\text{C}$)	5.2	A
I_{DM}	Drain Current - Pulsed (Note 1)	32.8	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	210	mJ
I_{AR}	Avalanche Current (Note 1)	8.2	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	4.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5.5	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	45	W
	- Derate above 25°C	0.36	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	2.78	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	62.5	$^\circ\text{C}/\text{W}$

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	200	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C	--	0.14	--	$V/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 200\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	μA
		$V_{DS} = 160\text{ V}, T_C = 125^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	3.0	--	5.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 4.1\text{ A}$	--	0.21	0.28	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 40\text{ V}, I_D = 4.1\text{ A}$ (Note 4)	--	7.1	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	700	910	pF
C_{oss}	Output Capacitance		--	125	160	pF
C_{rss}	Reverse Transfer Capacitance		--	18	25	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 100\text{ V}, I_D = 11.6\text{ A},$ $R_G = 25\text{ }\Omega$ (Note 4, 5)	--	13	35	ns
t_r	Turn-On Rise Time		--	120	250	ns
$t_{d(off)}$	Turn-Off Delay Time		--	30	70	ns
t_f	Turn-Off Fall Time		--	55	120	ns
Q_g	Total Gate Charge	$V_{DS} = 160\text{ V}, I_D = 11.6\text{ A},$ $V_{GS} = 10\text{ V}$ (Note 4, 5)	--	18	23	nC
Q_{gs}	Gate-Source Charge		--	5	--	nC
Q_{gd}	Gate-Drain Charge		--	8	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	8.2	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	32.8	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 8.2 A	--	--	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 11.6 A, dI _F / dt = 100 A/μs (Note 4)	--	130	--	ns
Q _{rr}	Reverse Recovery Charge		--	0.63	--	μC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 4.7\text{ mH}, I_{AS} = 8.2\text{ A}, V_{DD} = 50\text{ V}, R_G = 25\text{ }\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 11.6\text{ A}, dI/dt \leq 300\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics

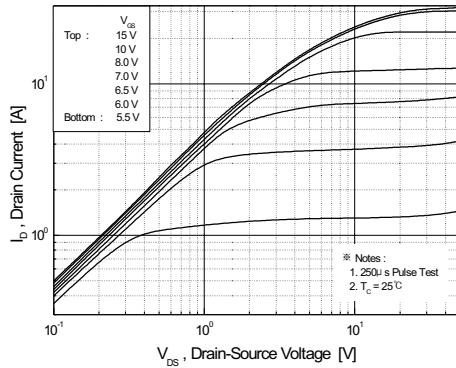


Figure 1. On-Region Characteristics

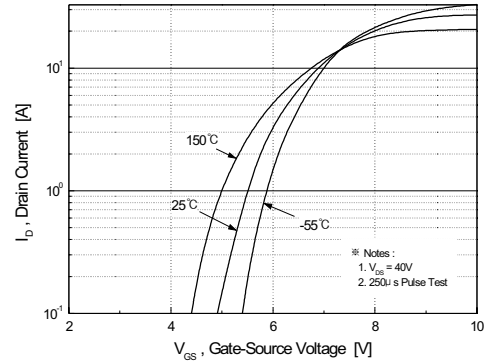


Figure 2. Transfer Characteristics

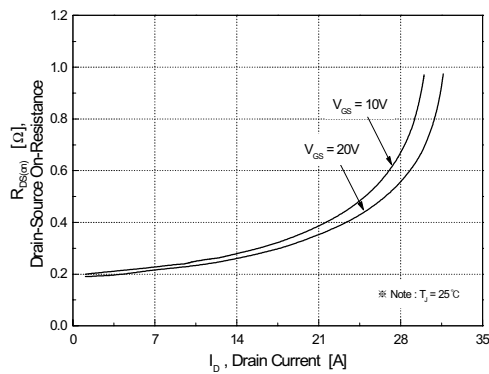


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

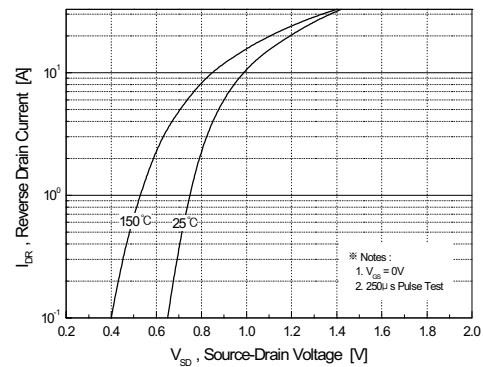


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

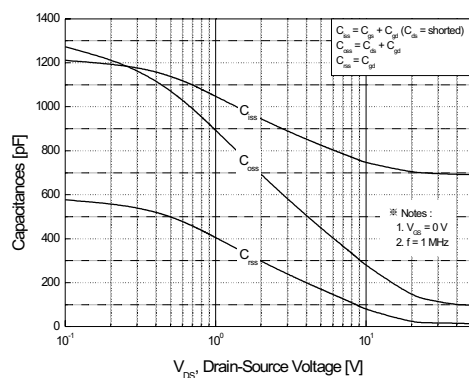


Figure 5. Capacitance Characteristics

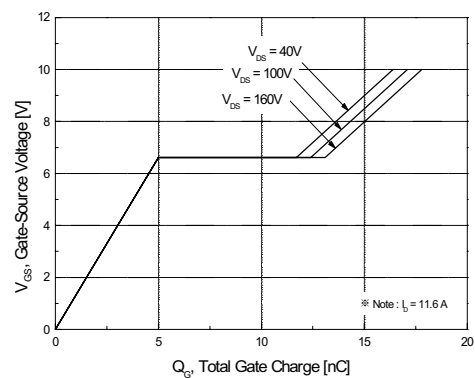


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

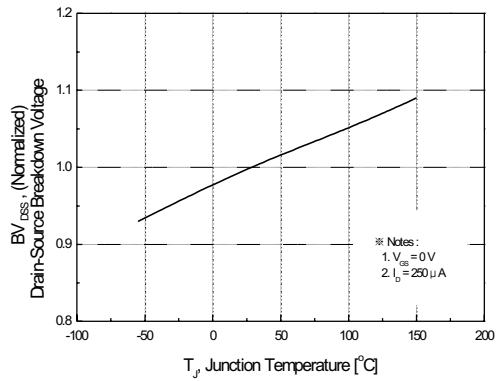


Figure 7. Breakdown Voltage Variation vs. Temperature

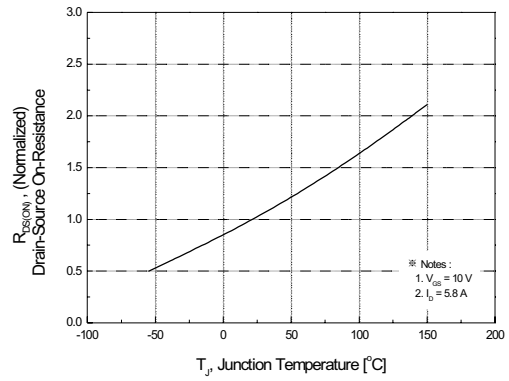


Figure 8. On-Resistance Variation vs. Temperature

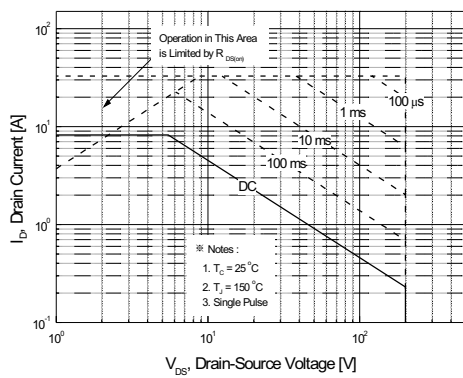


Figure 9. Maximum Safe Operating Area

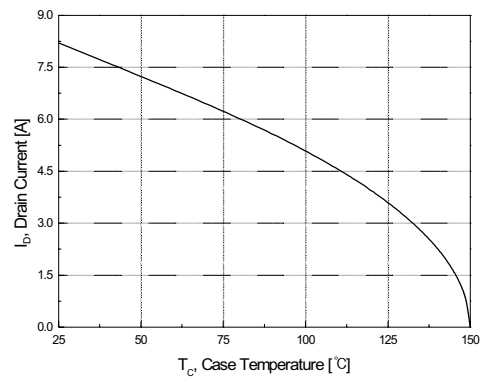


Figure 10. Maximum Drain Current vs. Case Temperature

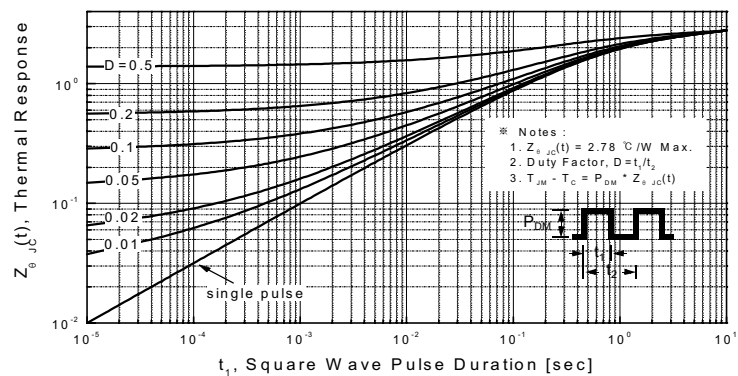
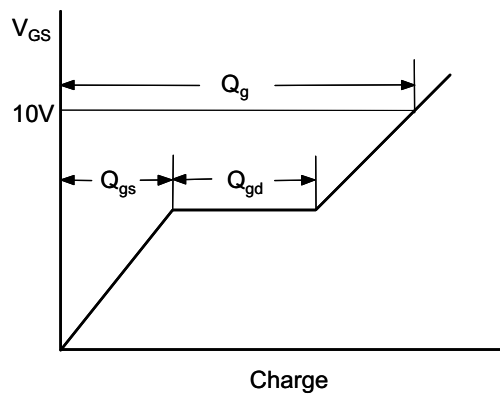
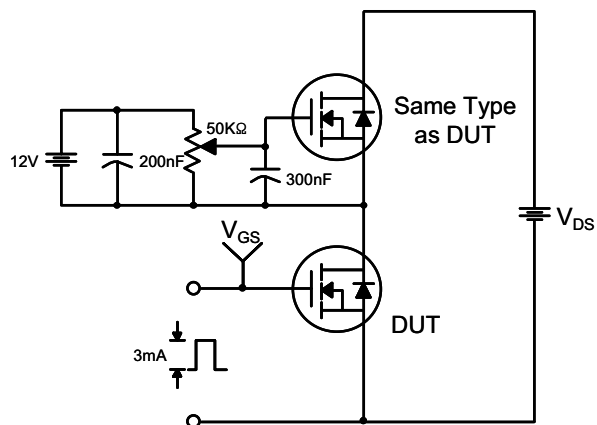
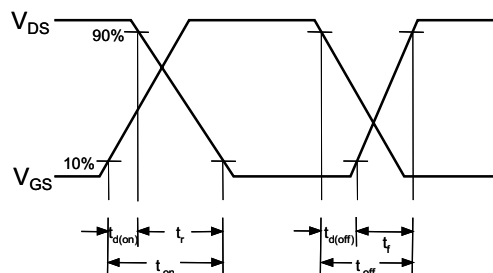
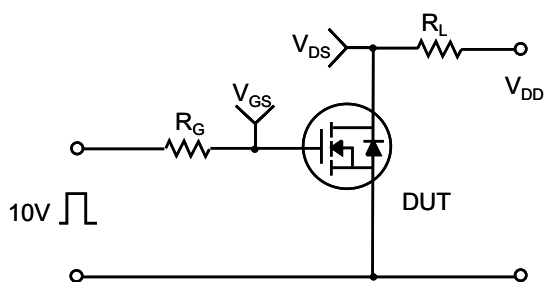


Figure 11. Transient Thermal Response Curve

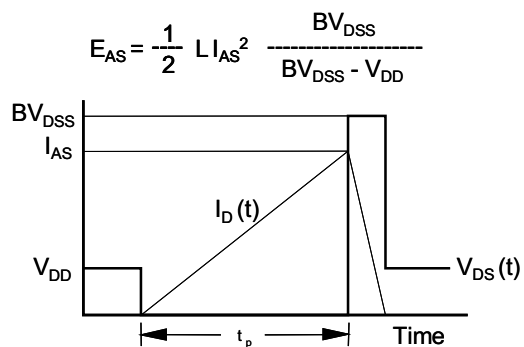
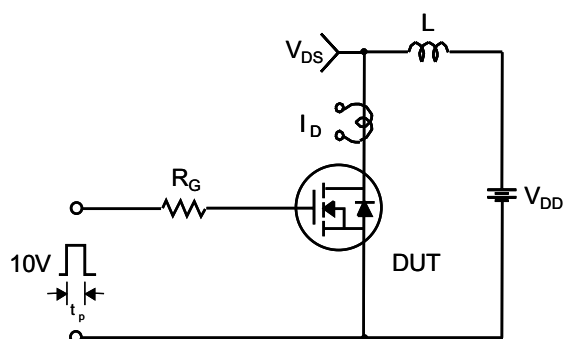
Gate Charge Test Circuit & Waveform



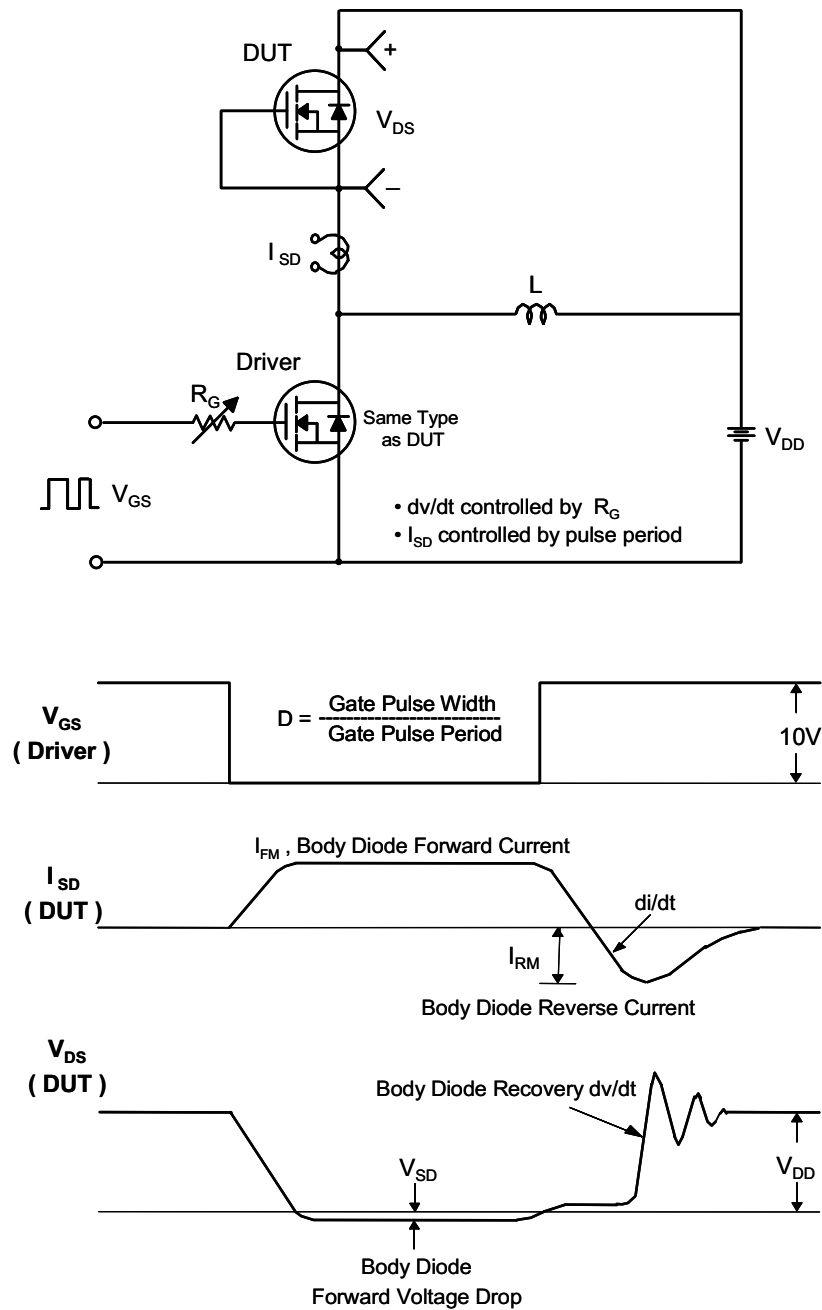
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms



Technical drawing of a mechanical part, showing three views: front view, side view, and bottom view. Dimensions are provided in millimeters (mm) with tolerances.

Front View Dimensions:

- Overall width: 10.16 ± 0.20
- Distance from left edge to center of top hole: (7.00)
- Top hole diameter: $\phi 3.18 \pm 0.10$
- Top hole spacing (center-to-center): 3.30 ± 0.10
- Overall height: 15.80 ± 0.20
- Bottom hole diameter: $\phi 3.18 \pm 0.10$
- Pin diameter: 0.35 ± 0.10
- Pin length (from base to top of pin): 9.75 ± 0.30
- Pin tip radius: $R1.47$
- Pin tip angle: (30°)
- Pin base width: 0.80 ± 0.10
- Pin base radius: $R0.35 \pm 0.10$
- Pin base diameter: 2.54 TYP [2.54 ± 0.20]

Side View Dimensions:

- Overall width: 2.54 ± 0.20
- Distance from left edge to center of top hole: (0.70)
- Top hole diameter: $\phi 3.18 \pm 0.10$
- Top hole spacing (center-to-center): 6.68 ± 0.20
- Overall height: 15.87 ± 0.20
- Bottom hole diameter: $\phi 3.18 \pm 0.10$
- Pin diameter: 0.35 ± 0.10
- Pin length (from base to top of pin): 9.75 ± 0.30
- Pin tip radius: $R1.47$
- Pin tip angle: (30°)
- Pin base width: 0.80 ± 0.10
- Pin base radius: $R0.35 \pm 0.10$
- Pin base diameter: 2.54 TYP [2.54 ± 0.20]

Bottom View Dimensions:

- Overall width: 9.40 ± 0.20
- Overall height: 4.70 ± 0.20

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